

Document Number: MPX2300DT1 Rev. 11, 09/2015



## MPX2300DT1, 0 to 40 kPa, Differential Compensated Pressure Sensor

Freescale Semiconductor has developed a high volume, miniature pressure sensor package which is ideal as a sub-module component or a disposable unit. The unique concept of the Chip Pak allows great flexibility in system design while providing an economic solution for the designer. This new chip carrier package uses Freescale Semiconductor's unique sensor die with its piezoresistive technology, along with the added feature of on-chip, thin-film temperature compensation and calibration.

#### Features

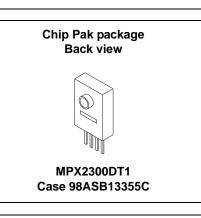
- Integrated temperature compensation and calibration
- Ratiometric to supply voltage
- Polysulfone case material (ISO 10993)
- Provided in easy-to-use tape and reel

### Typical applications

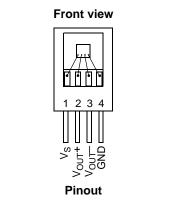
- Medical diagnostics
- Infusion pumps
- Blood pressure monitors
- Pressure catheter applications
- Patient monitoring

### NOTE

The die and wire bonds are exposed on the front side of the chip pak (pressure is applied to the backside of the device). Front side die and wire protection must be provided in the customer's housing. Use caution when handling the devices during all processes.



**MPX2300DT1** 



Ordering information							
Davias nome	Chinging			Pressure type		Device models	
Device name	Shipping	Package	Gauge	Differential	Absolute	Device marking	
MPX2300DT1	Tape and Reel	98ASB13355C		•		XXXX = Device code XXX = Trace code	

Freescale reserves the right to change the detail specifications as may be required to permit improvements in the design of its products.

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### **Related Documentation**

The MPX2300DT1 device features and operations are described in a variety of reference manuals, user guides, and application notes. To find the most-current versions of these documents:

1. Go to the Freescale homepage at:

#### http://www.freescale.com/

- 2. In the Keyword search box at the top of the page, enter the device number MPX2300DT1.
- 3. In the Refine Your Result pane on the left, click on the Documentation link.

#### MPX2300DT1



### 1 General Description

The MPX2300DT1 pressure sensor has been designed for medical usage by combining the performance of Freescale's shear stress pressure sensor design and the use of biomedically approved materials. Materials with a proven history in medical situations have been chosen to provide a sensor that can be used with confidence in applications, such as invasive blood pressure monitoring. It can be sterilized using ethylene oxide. The portions of the pressure sensor that are required to be biomedically approved are the rigid housing and the gel coating.

The rigid housing is molded from a white, medical grade polysulfone that has passed extensive biological testing including: ISO 10993-5:1999, ISO 10993-10:2002, and ISO 10993-11:1993.

A silicone dielectric gel covers the silicon piezoresistive sensing element. The gel is a nontoxic, nonallergenic elastomer system which meets all USP XX Biological Testing Class V requirements. The properties of the gel allow it to transmit pressure uniformly to the diaphragm surface, while isolating the internal electrical connections from the corrosive effects of fluids, such as saline solution. The gel provides electrical isolation sufficient to withstand defibrillation testing, as specified in the proposed Association for the Advancement of Medical Instrumentation (AAMI) Standard for blood pressure transducers. A biomedically approved opaque filler in the gel prevents bright operating room lights from affecting the performance of the sensor.

### 1.1 Block diagram

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

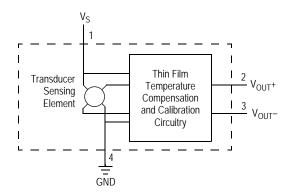


Figure 1. Block diagram

1.2 Pinout

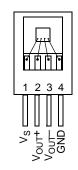


Figure 2. Device pinout (front view)

#### Table 1. Pin functions

Pin	Name	Function
1	V <sub>S</sub>	Voltage supply
2	V <sub>OUT</sub> +	Output voltage
3	V <sub>OUT</sub> -	Output voltage
4	GND	Ground

MPX2300DT1



### 2 Mechanical and Electrical Specifications

### 2.1 Maximum ratings

### Table 2. Maximum ratings<sup>(1)</sup>

Rating	Symbol	Value	Unit
Maximum pressure (backside)	P <sub>max</sub>	125	PSI
Storage temperature	T <sub>stg</sub>	-25 to +85	°C
Operating temperature	T <sub>A</sub>	+15 to +40	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

### 2.2 Operating characteristics

Table 3. Operating characteristics ( $V_S = 6 V_{DC}$ ,  $T_A = 25 \degree C$  unless otherwise noted)

Characteristics	Symbol	Min	Тур	Max	Unit
Pressure range	P <sub>OP</sub>	0	_	300	mmHg
Supply voltage <sup>(1)</sup>	V <sub>S</sub>		6.0	10	V <sub>DC</sub>
Supply current	Ι <sub>Ο</sub>	_	1.0	_	mAdc
Zero pressure offset	V <sub>OFF</sub>	-0.75	_	0.75	mV
Sensitivity	—	4.95	5.0	5.05	μV/V/mmHg
Full-scale span <sup>(2)</sup>	V <sub>FSS</sub>	2.976	3.006	3.036	mV
Linearity + Hysteresis <sup>(3)</sup>	—	-1.5	_	1.5	%V <sub>FSS</sub>
Accuracy $V_S = 6 V, P = 101 \text{ to } 200 \text{ mmHg}$	_	-1.5	—	1.5	%
Accuracy $V_S = 6 V, P = 201 \text{ to } 300 \text{ mmHg}$	—	-3.0	_	3.0	%
Temperature effect on sensitivity	TCS	-0.1	_	+0.1	%/°C
Temperature effect on full-scale span <sup>(4)</sup>	TCV <sub>FSS</sub>	-0.1	—	+0.1	%/°C
Temperature effect on offset <sup>(5)</sup>	TCV <sub>OFF</sub>	-9.0	_	+9.0	μV/°C
Input impedance	Z <sub>IN</sub>	1800	_	4500	Ω
Output impedance	Z <sub>OUT</sub>	270	—	330	Ω
$R_{CAL}$ (150 kΩ) <sup>(6)</sup>	R <sub>CAL</sub>	97	100	103	mmHg
Response time <sup>(7)</sup> (10% to 90%)	t <sub>R</sub>	_	1.0	—	ms

 Recommended voltage supply: 6 V ± 0.2 V, regulated. Sensor output is ratiometric to the voltage supply. Supply voltages above +10 V may induce additional error due to device self-heating.

 Measured at 6.0 V<sub>DC</sub> excitation for 100 mmHg pressure differential. V<sub>FSS</sub> and FSS are like terms representing the algebraic difference between full scale output and zero pressure offset.

3. Maximum deviation from end-point straight line fit at 0 and 200 mmHg.

4. Slope of end-point straight line fit to full scale span at 15 °C and +40 °C relative to +25 °C.

5. Slope of end-point straight line fit to zero pressure offset at 15 °C and +40 °C relative to +25 °C.

6. Offset measurement with respect to the measured sensitivity when a 150 k resistor is connected to V<sub>S</sub> and V<sub>OUT</sub>+ output.

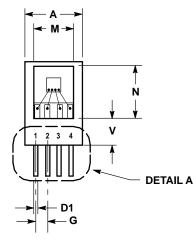
7. For a 0 to 300 mmHg pressure step change.



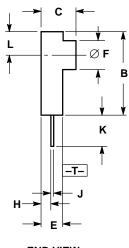
## 3 Package Dimensions

### 3.1 Package description

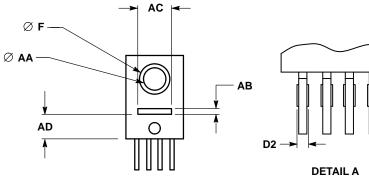
This drawing is located at http://cache.freescale.com/files/shared/doc/package\_info/98ASB13355C.pdf.







END VIEW





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIN	IETERS
DIM	MIN MAX		MIN	MAX
Α	0.240	0.260	6.10	6.60
В	0.350	0.370	8.89	9.40
С	0.140	0.150	3.56	3.81
D1	0.012	0.020	0.30	0.51
D2	0.014	0.022	0.36	0.56
Е	0.088	0.102	2.24	2.59
F	0.123	0.128	3.12	3.25
G	0.045	0.055	1.14	1.40
Н	0.037	0.047	0.94	1.19
J	0.007	0.011	0.18	0.28
K	0.120	0.140	3.05	3.56
L	0.095	0.105	2.41	2.67
М	0.165	0.175	4.19	4.45
Ν	0.223	0.239	5.66	6.07
٧	0.105	0.115	2.67	2.92
AA	0.095	0.107	2.41	2.72
AB	0.015	0.035	0.38	0.89
AC	0.120	0.175	3.05	4.45
AD	0.100	0.115	2.54	2.92

Case 98ASB1335C, Chip Pak package



## 4 Revision History

#### Table 4. Revision history

Revision number	Revision date	Description
9	10/2012	Added Table 1. Pin Numbers on page 1.
10	09/2015	Updated format.
11	<ul> <li>09/2015</li> <li>Corrected pinout on first page and Section 1.2 and Table 1.</li> <li>Replaced Figure 1, Block diagram.</li> </ul>	

#### MPX2300DT1



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